

Product Compliance Declaration

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Contact Information

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Part Information

Part Number 0348978200 Part Weight 3.44G

Part Name MINI50 RAHDR SMT 20CKT BLK POL A T&R

Product Composition

Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
MINI50 RAHDR SMT 20CKT BLK POL A T&R	Assembly		100	3.44
MINI50 HSNG RAHDR SMT 20CKT BLK POL A	Component		75.8721	2.61
PS-ST GF30 Black	Material		75.8721	2.61
PS-ST	Substance		44.34	1.525294
GF-Fibre	Substance		22.8953	0.787599
Pigment portion, not to declare	Substance	system	0.5032	0.01731
Further Additives, not to declare	Substance	system	2.343	0.080599
Benzene, ethenyl-, polymer with 1,3-butadiene, hydrogenated	Substance	66070-58-4	5.7906	0.199198
MINI50 TERM SMT SOLDER NAIL LT MATTE SN	Component		3.8663	0.133
Cartridge Brass 70% Unplated	Material		3.6337	0.125
Copper	Substance	7440-50-8	2.5436	0.0875
Zinc (metal)	Substance	7440-66-6	1.0901	0.0375
Nickel Plating	Material		0.0814	0.0028

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Nickel	Substance	7440-02-0	0.0814	0.0028
Further Additives, not to declare	Substance	system	8E-06	3E-07
Tin Plating	Material		0.1512	0.0052
Tin	Substance	7440-31-5	0.1512	0.0052
MINI50 TERM SMT SOLDER NAIL RT MATTE SN	Component		3.6337	0.125
Cartridge Brass 70% Unplated	Material		3.4012	0.117
Copper	Substance	7440-50-8	2.3808	0.0819
Zinc (metal)	Substance	7440-66-6	1.0203	0.0351
Nickel Plating	Material		0.0814	0.0028
Nickel	Substance	7440-02-0	0.0814	0.0028
Further Additives, not to declare	Substance	system	8E-06	3E-07
Tin Plating	Material		0.1512	0.0052
Tin	Substance	7440-31-5	0.1512	0.0052
MINI50 TERM BLD 0.50X15.57 MATTE SN	Component		9.4186	0.324
Cartridge Brass 70% Unplated	Material		8.3721	0.288
Copper	Substance	7440-50-8	5.8605	0.2016
Zinc (metal)	Substance	7440-66-6	2.5116	0.0864
Nickel Plating	Material		0.4186	0.0144
Nickel	Substance	7440-02-0	0.4186	0.014399
Further Additives, not to declare	Substance	system	4E-05	0.000001
Tin Plating	Material		0.6279	0.0216
Tin	Substance	7440-31-5	0.6279	0.0216
MINI50 TERM BLD 0.50X17.77 MATTE SN	Component		7.2093	0.248
Cartridge Brass 70% Unplated	Material		6.5116	0.224
Copper	Substance	7440-50-8	4.5581	0.1568
Zinc (metal)	Substance	7440-66-6	1.9535	0.0672
Nickel Plating	Material		0.2791	0.0096
Nickel	Substance	7440-02-0	0.279	0.009599
Further Additives, not to declare	Substance	system	3E-05	1E-06

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Name	Туре	CAS Number	Proportion (% Total)	Mass (Grams)
Tin Plating	Material		0.4186	0.0144
Tin	Substance	7440-31-5	0.4186	0.0144

ROHS Declaration Information

Regulatory Revision EU 2015/863

Compliance Status Compliant

Contained Substances Exceeding Threshold

None

Exemptions

None

REACH-SVHC Declaration Information

Regulatory Revision D(2020)9139-DC (19 Jan 2021)

Contained Substances Exceeding Threshold

None

GADSL Declaration Information

Regulatory Revision GADSL imported from IMDS

Contained Substances Exceeding Threshold

Substance Group	Substance Location	Threshold (PPM)	Concentration (PPM)	Intentionally Added
lead	Cartridge Brass 70% (CA260)	*Note	350	Yes
lead		*Note	500	Yes
nickel powder [particle diameter < 1 mm]	Ep-Ni	*Note	997,500	Yes
copper	Cartridge Brass 70% (CA260)	*Note	700,000	Yes
glass, oxide, chemicals	PS-ST GF30 Black	*Note	320,000	Yes

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*Note: For GADSL substance declarable/prohibited threshold values, please reference http://www.gadsl.org/

Exemptions

Part Name	Exemption
Cartridge Brass 70% (CA260)	44 Concentration within acceptable GADSL limits
	44 Concentration within acceptable GADSL limits
Ep-Ni	33 Other application (Surface not routinely touched or nickel release rate < 0.5µg/cm2/week)

HFLH Declaration Information

Regulatory Revision IEC 61249-2-21

Contained Substances Exceeding Threshold

None

China ROHS Declaration Information

Part Number	0348978200							
Part Name	MINI50 RAHDR SMT 20CKT BLK POL A T&R	(e)						
Part Information	on			Haz	zardous S	Substance	s	
Components			Lead	Mercury	Cadmium	Hex. Chromium	PBB	PBDE
MINI50 RAHI	DR SMT 20CKT BLK POL A T&R		0	0	0	0	0	0
MINI50 HSNO	G RAHDR SMT 20CKT BLK POL A		0	0	0	0	0	0
MINI50 TERM	M SMT SOLDER NAIL LT MATTE SN		0	0	0	0	0	0
MINI50 TERM	M SMT SOLDER NAIL RT MATTE SN		0	0	0	0	0	0
MINI50 TERM	M BLD 0.50X15.57 MATTE SN		0	0	0	0	0	0
MINI50 TERM	M BLD 0.50X17.77 MATTE SN		0	0	0	0	0	0

Process Information

Component Plating / Surface Finish	N/A
Termination Base Alloy	N/A

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Solder Alloy	N/A
Process Capability	N/A
Maximum Exposure Time (seconds)	N/A
Maximum Process Temperature (C)	N/A
Maximum Cycles at Reflow Temperature	N/A
J-STD-020 Moisture Sensitivity Level	N/A

Feb 24, 2021